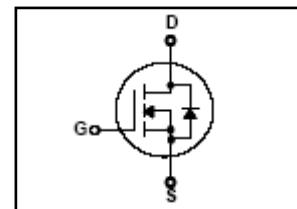
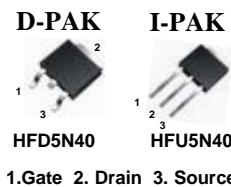


HFD5N40 / HFU5N40 400V N-Channel MOSFET

FEATURES

- Originative New Design
- Superior Avalanche Rugged Technology
- Robust Gate Oxide Technology
- Very Low Intrinsic Capacitances
- Excellent Switching Characteristics
- Unrivalled Gate Charge : 13 nC (Typ.)
- Extended Safe Operating Area
- Lower $R_{DS(ON)}$: 1.27 Ω (Typ.) @ $V_{GS}=10V$
- 100% Avalanche Tested

$BV_{DSS} = 400 V$
 $R_{DS(on)\ typ} = 1.27 \Omega$
 $I_D = 3.4 A$



Absolute Maximum Ratings $T_C=25^\circ C$ unless otherwise specified

Symbol	Parameter	Value	Units
V_{DSS}	Drain-Source Voltage	400	V
I_D	Drain Current – Continuous ($T_C = 25^\circ C$)	3.4	A
	Drain Current – Continuous ($T_C = 100^\circ C$)	2.15	A
I_{DM}	Drain Current – Pulsed (Note 1)	13.6	A
V_{GS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	510	mJ
I_{AR}	Avalanche Current (Note 1)	3.4	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	4.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
P_D	Power Dissipation ($T_A = 25^\circ C$)	2.5	W
	Power Dissipation ($T_C = 25^\circ C$) - Derate above $25^\circ C$	45	W
		0.36	W/ $^\circ C$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ C$

Thermal Resistance Characteristics

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	--	2.78	$^\circ C/W$
$R_{\theta JA}$	Junction-to-Ambient*	--	50	
$R_{\theta CA}$	Junction-to-Ambient	--	110	

* When mounted on the minimum pad size recommended (PCB Mount)

Electrical Characteristics $T_C=25^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
On Characteristics						
V_{GS}	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	2.5	--	4.5	V
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}$, $I_D = 1.7 \text{ A}$	--	1.27	1.6	Ω

Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	400	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C	--	0.38	--	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 400 \text{ V}$, $V_{GS} = 0 \text{ V}$	--	--	1	μA
		$V_{DS} = 320 \text{ V}$, $T_C = 125^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}$, $V_{DS} = 0 \text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}$, $V_{DS} = 0 \text{ V}$	--	--	-100	nA

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1.0 \text{ MHz}$	--	450	590	pF
C_{oss}	Output Capacitance		--	70	90	pF
C_{rss}	Reverse Transfer Capacitance		--	10	17	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Time	$V_{DS} = 200 \text{ V}$, $I_D = 4.5 \text{ A}$, $R_G = 25 \Omega$ (Note 4,5)	--	15	30	ns
t_r	Turn-On Rise Time		--	70	140	ns
$t_{d(off)}$	Turn-Off Delay Time		--	30	60	ns
t_f	Turn-Off Fall Time		--	40	80	ns
Q_g	Total Gate Charge	$V_{DS} = 320 \text{ V}$, $I_D = 4.5 \text{ A}$, $V_{GS} = 10 \text{ V}$ (Note 4,5)	--	13	17	nC
Q_{gs}	Gate-Source Charge		--	4.0	--	nC
Q_{gd}	Gate-Drain Charge		--	6.0	--	nC

Source-Drain Diode Maximum Ratings and Characteristics

I_S	Continuous Source-Drain Diode Forward Current	--	--	3.4	A	
I_{SM}	Pulsed Source-Drain Diode Forward Current	--	--	13.6		
V_{SD}	Source-Drain Diode Forward Voltage	$I_S = 3.4 \text{ A}$, $V_{GS} = 0 \text{ V}$	--	--	1.5	V
trr	Reverse Recovery Time	$I_S = 4.5 \text{ A}$, $V_{GS} = 0 \text{ V}$ $di_F/dt = 100 \text{ A}/\mu\text{s}$ (Note 4)	--	190	--	ns
Qrr	Reverse Recovery Charge		--	1.0	--	μC

Notes :

- Repetitive Rating : Pulse width limited by maximum junction temperature
- $L=44\text{mH}$, $I_{AS}=4.5\text{A}$, $V_{DD}=50\text{V}$, $R_G=25\Omega$, Starting $T_J=25^\circ\text{C}$
- $I_{SD}\leq 3.4\text{A}$, $di/dt\leq 200\text{A}/\mu\text{s}$, $V_{DD}\leq BV_{DSS}$, Starting $T_J=25^\circ\text{C}$
- Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$
- Essentially Independent of Operating Temperature

Typical Characteristics

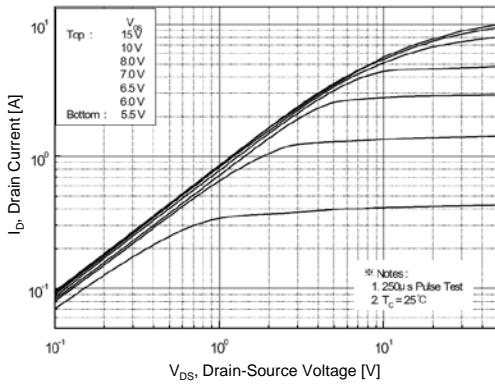


Figure 1. On Region Characteristics

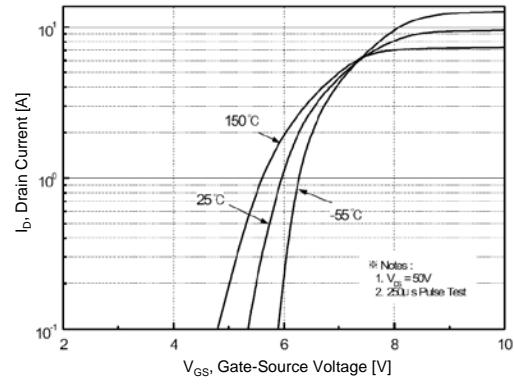


Figure 2. Transfer Characteristics

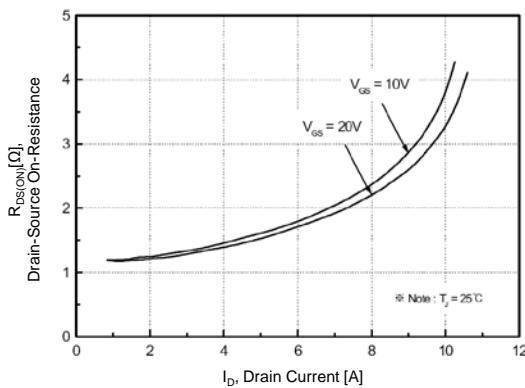


Figure 3. On Resistance Variation vs. Drain Current and Gate Voltage

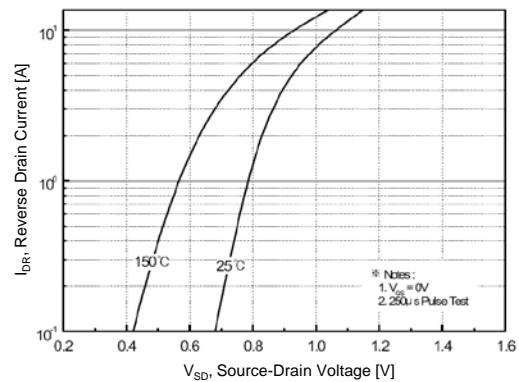


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

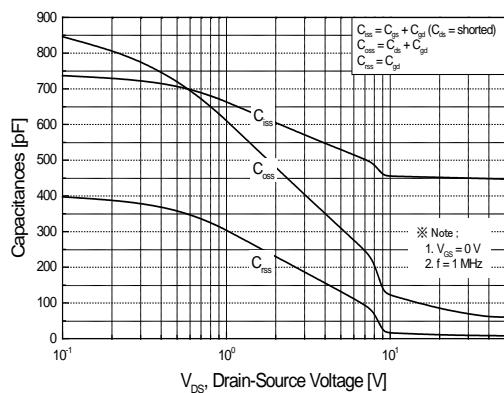


Figure 5. Capacitance Characteristics

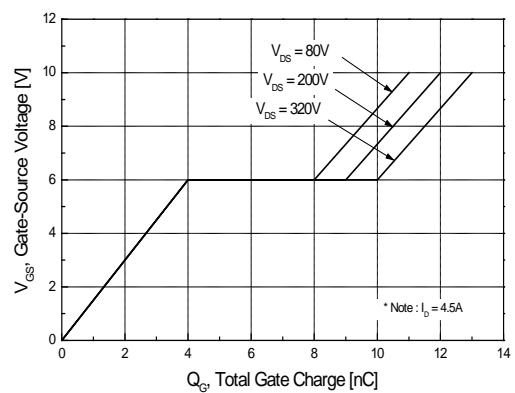
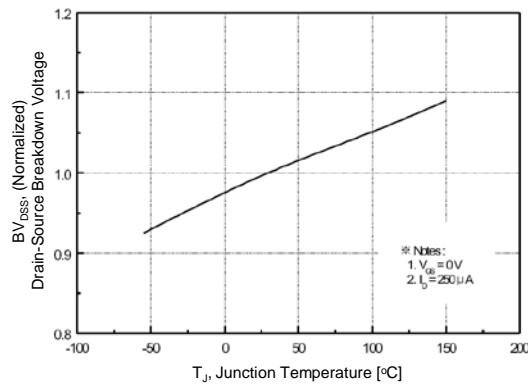
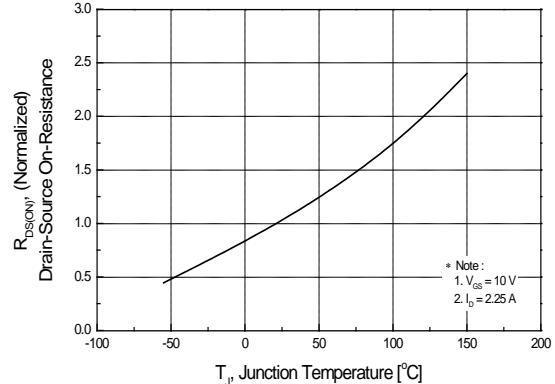


Figure 6. Gate Charge Characteristics

Typical Characteristics (continued)



**Figure 7. Breakdown Voltage Variation
vs Temperature**



**Figure 8. On-Resistance Variation
vs Temperature**

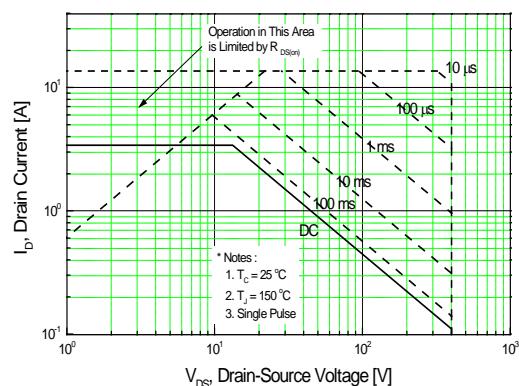
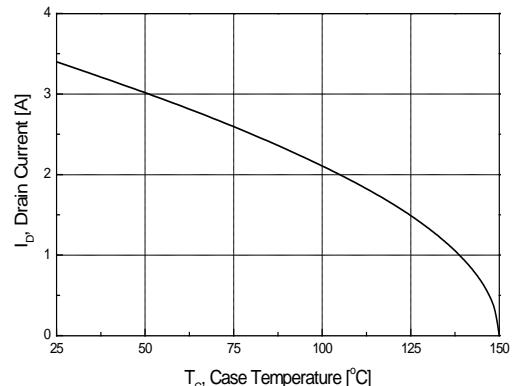


Figure 9. Maximum Safe Operating Area



**Figure 10. Maximum Drain Current
vs Case Temperature**

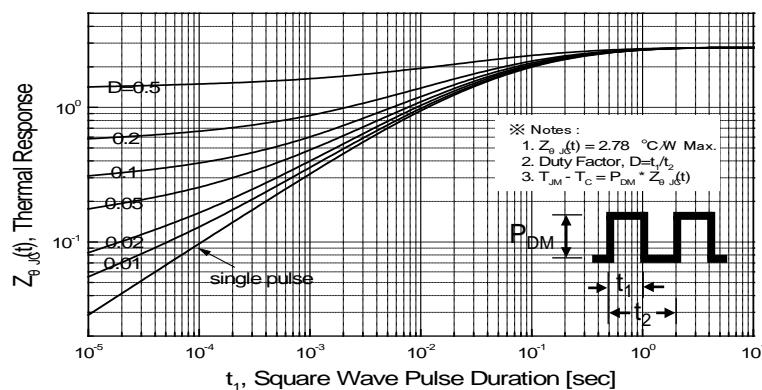


Figure 11. Transient Thermal Response Curve

Fig 12. Gate Charge Test Circuit & Waveform

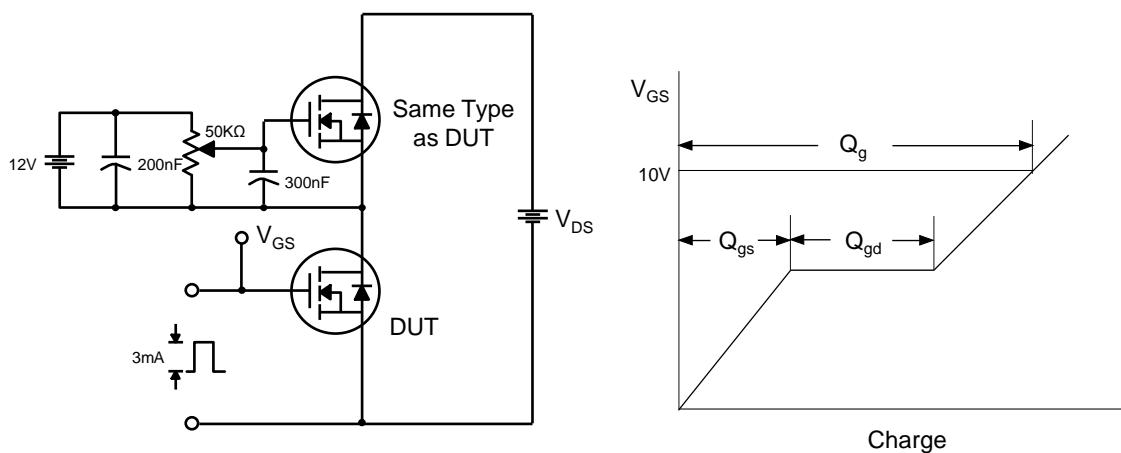


Fig 13. Resistive Switching Test Circuit & Waveforms

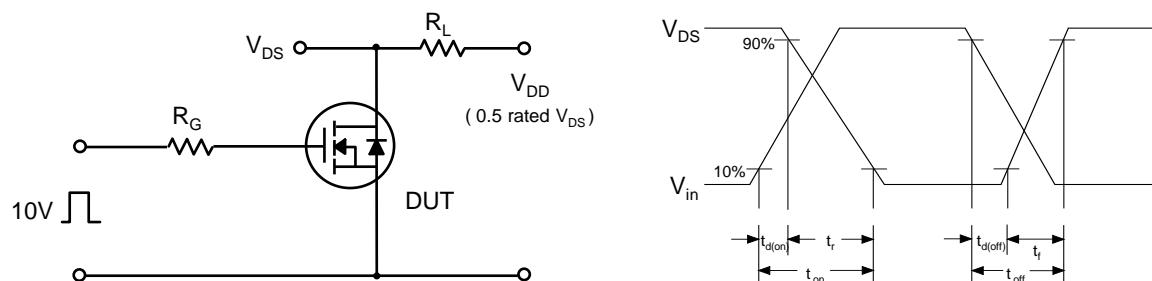


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

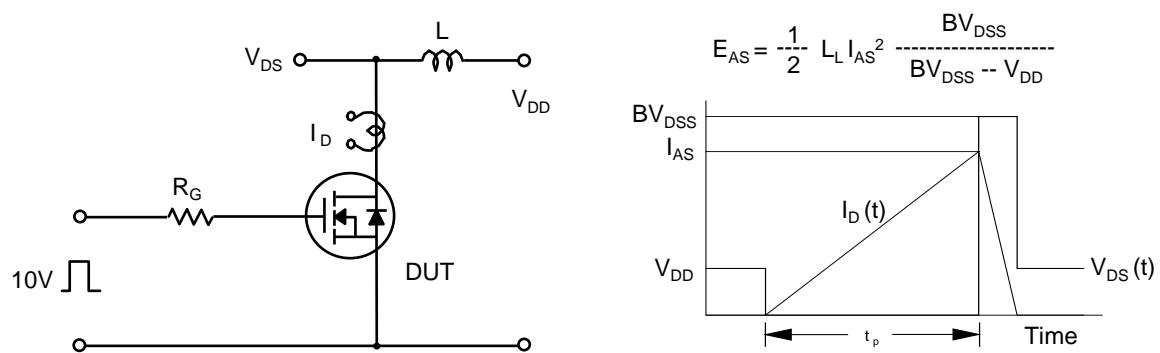
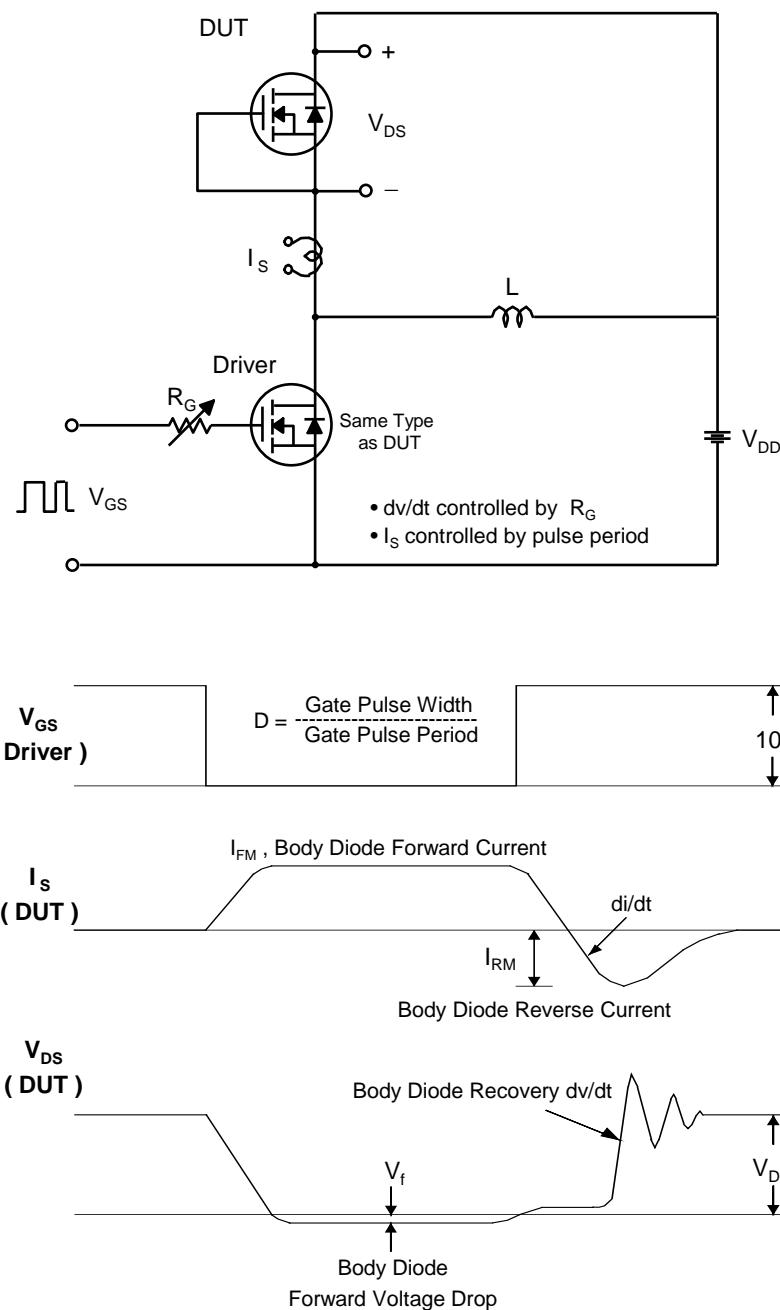


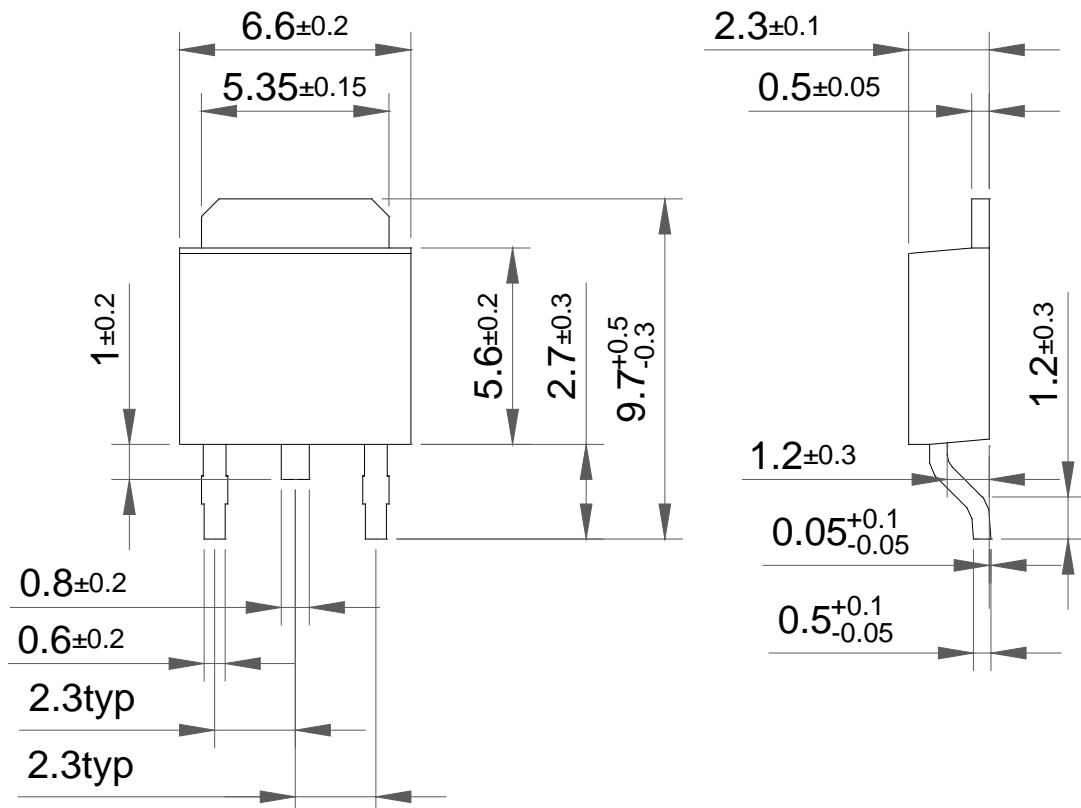
Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



HFD5N40 / HFU5N40

Package Dimension

TO-252



HFD5N40 / HFU5N40

TO-251

